



NX3008NBKV

30 V, 400 mA dual N-channel Trench MOSFET

Rev. 1 — 1 August 2011

Product data sheet

1. Product profile

1.1 General description

Dual N-channel enhancement mode Field-Effect Transistor (FET) in an ultra small and flat lead SOT666 Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Very fast switching
- Low threshold voltage
- Trench MOSFET technology
- ESD protection up to 2 kV
- AEC-Q101 qualified

1.3 Applications

- Relay driver
- High-speed line driver
- Low-side loadswitch
- Switching circuits

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$	-	-	30	V
V_{GS}	gate-source voltage		-8	-	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25^\circ\text{C}$	[1]	-	400	mA
Static characteristics (per transistor)						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}; I_D = 350\text{ mA}; T_j = 25^\circ\text{C}$	-	1	1.4	Ω

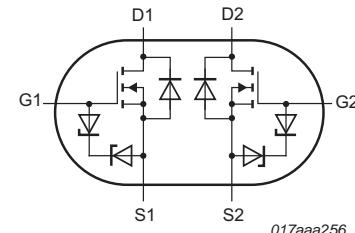
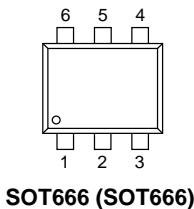
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm².



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S1	source TR1		
2	G1	gate TR1		
3	D2	drain TR2		
4	S2	source TR2		
5	G2	gate TR2		
6	D1	drain TR1		



3. Ordering information

Table 3. Ordering information

Type number	Package	Name	Description	Version
NX3008NBKV	SOT666		plastic surface-mounted package; 6 leads	SOT666

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
NX3008NBKV	AA

[1] % = placeholder for manufacturing site code.

5. Limiting values

Table 5. Limiting values

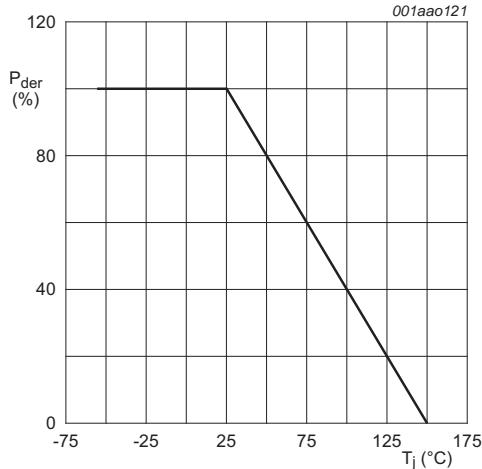
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor					
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$	-	30	V
V_{GS}	gate-source voltage		-8	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25^\circ\text{C}$	[1]	-	400 mA
		$V_{GS} = 4.5\text{ V}; T_{amb} = 100^\circ\text{C}$	[1]	-	260 mA
I_{DM}	peak drain current	$T_{amb} = 25^\circ\text{C}$; single pulse; $t_p \leq 10\ \mu\text{s}$	-	1.6	A
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$	[2]	-	330 mW
			[1]	-	390 mW
		$T_{sp} = 25^\circ\text{C}$	-	1090	mW
Per device					
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$	[2]	-	500 mW
T_j	junction temperature		-55	150	°C
T_{amb}	ambient temperature		-55	150	°C
T_{stg}	storage temperature		-65	150	°C
Source-drain diode					
I_S	source current	$T_{amb} = 25^\circ\text{C}$	-	400	mA
ESD maximum rating					
V_{ESD}	electrostatic discharge voltage	HBM	[3]	-	2000 V

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm².

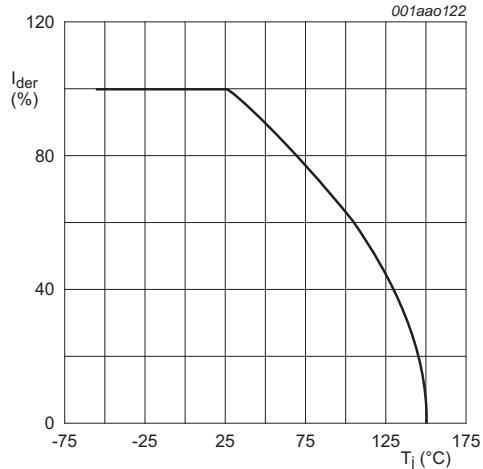
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



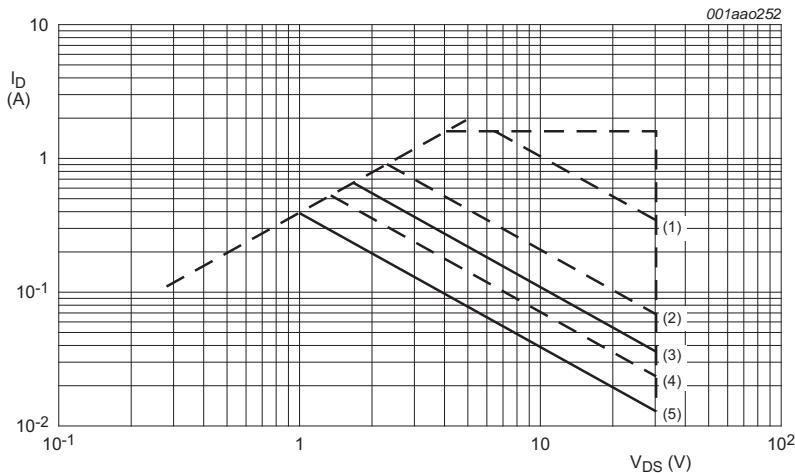
$$P_{der} = \frac{P_{tot}}{P_{tot}(25^\circ C)} \times 100 \%$$

Fig 1. Normalized total power dissipation as a function of junction temperature



$$I_{der} = \frac{I_D}{I_D(25^\circ C)} \times 100 \%$$

Fig 2. Normalized continuous drain current as a function of junction temperature



I_{DM} is a single pulse

- (1) $t_p = 1$ ms
- (2) $t_p = 10$ ms
- (3) DC; $T_{sp} = 25$ °C
- (4) $t_p = 100$ ms
- (5) DC; $T_{amb} = 25$ °C; 1 cm² drain mounting pad

Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

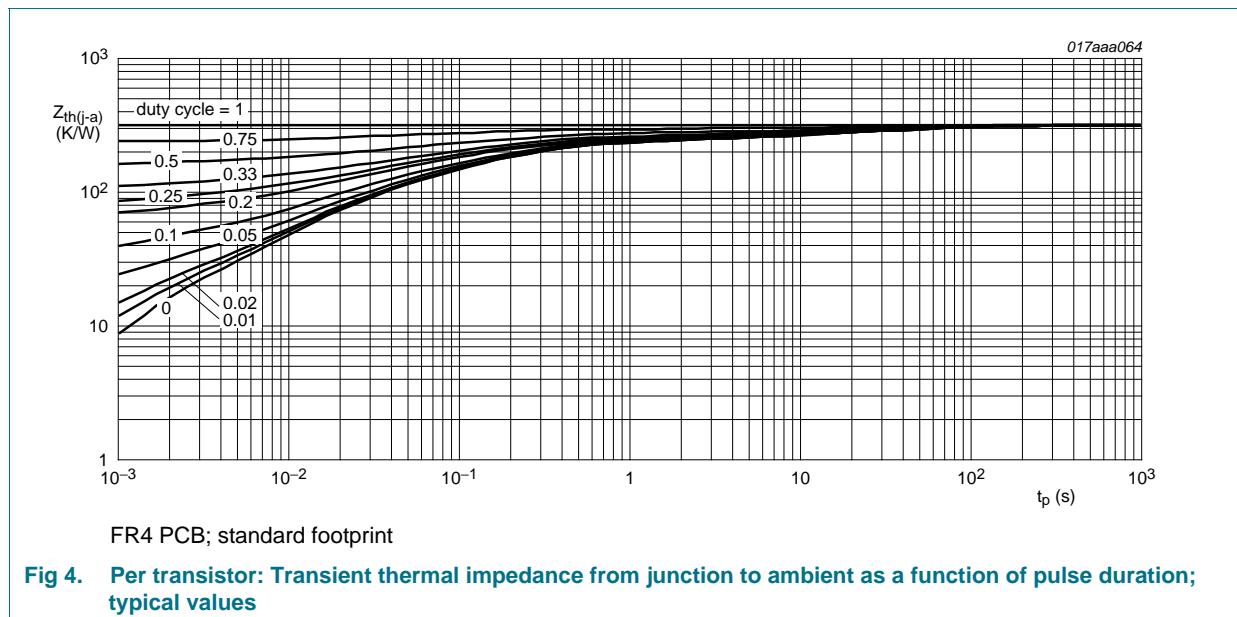
6. Thermal characteristics

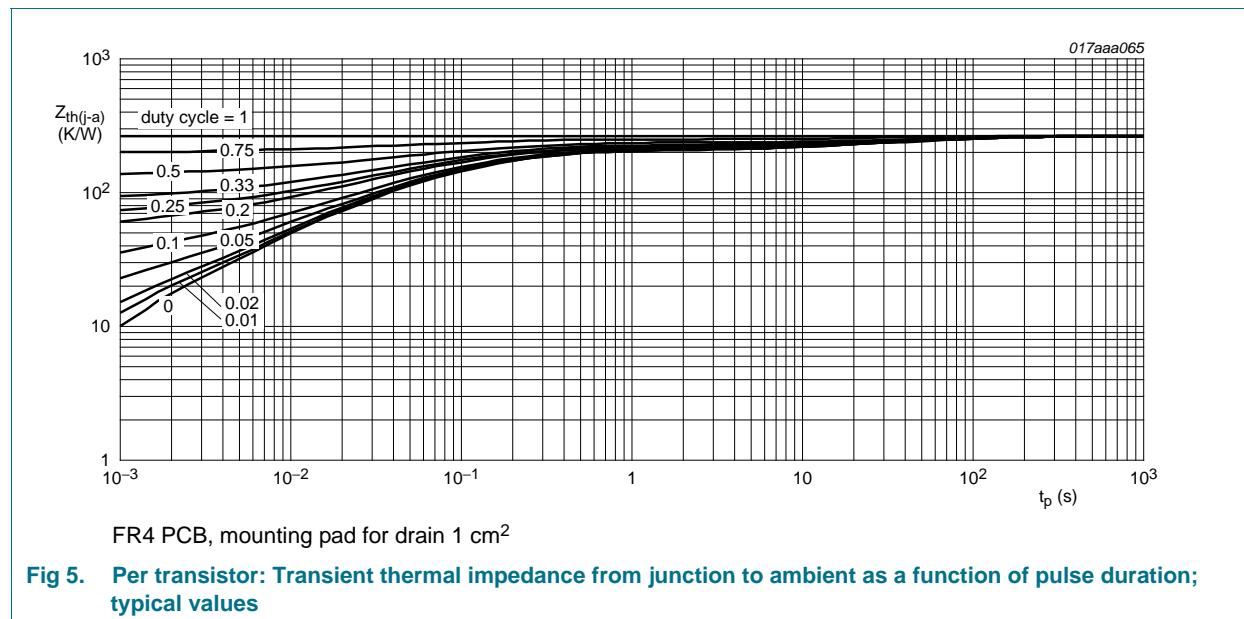
Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	330	380	K/W
			[2] -	280	320	K/W
$R_{th(j-sp)}$ thermal resistance from junction to solder point						
Per device						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	250	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².





7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics (per transistor)						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A$; $V_{GS} = 0 V$; $T_j = 25^\circ C$	30	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu A$; $V_{DS} = V_{GS}$; $T_j = 25^\circ C$	0.6	0.9	1.1	V
I_{DSS}	drain leakage current	$V_{DS} = 30 V$; $V_{GS} = 0 V$; $T_j = 25^\circ C$	-	-	1	μA
		$V_{DS} = 30 V$; $V_{GS} = 0 V$; $T_j = 150^\circ C$	-	-	10	μA
I_{GSS}	gate leakage current	$V_{GS} = 8 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	0.2	1	μA
		$V_{GS} = -8 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	0.2	1	μA
		$V_{GS} = 4.5 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	10	-	nA
		$V_{GS} = -4.5 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	10	-	nA
		$V_{GS} = 2.5 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	1	-	nA
		$V_{GS} = -2.5 V$; $V_{DS} = 0 V$; $T_j = 25^\circ C$	-	1	-	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 V$; $I_D = 350 mA$; $T_j = 25^\circ C$	-	1	1.4	Ω
		$V_{GS} = 4.5 V$; $I_D = 350 mA$; $T_j = 150^\circ C$	-	1.8	2.5	Ω
		$V_{GS} = 2.5 V$; $I_D = 200 mA$; $T_j = 25^\circ C$	-	1.4	2.1	Ω
		$V_{GS} = 1.8 V$; $I_D = 10 mA$; $T_j = 25^\circ C$	-	2	2.8	Ω
g_{fs}	forward transconductance	$V_{DS} = 10 V$; $I_D = 350 mA$; $T_j = 25^\circ C$	-	310	-	mS
Dynamic characteristics (per transistor)						
$Q_{G(tot)}$	total gate charge	$V_{DS} = 15 V$; $I_D = 400 mA$; $V_{GS} = 4.5 V$; $T_j = 25^\circ C$	-	0.52	0.68	nC
Q_{GS}	gate-source charge	$T_j = 25^\circ C$	-	0.17	-	nC
Q_{GD}	gate-drain charge		-	0.08	-	nC
C_{iss}	input capacitance	$V_{DS} = 15 V$; $f = 1 MHz$; $V_{GS} = 0 V$	-	34	50	pF
C_{oss}	output capacitance	$T_j = 25^\circ C$	-	6.5	-	pF
C_{rss}	reverse transfer capacitance		-	2.2	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 20 V$; $R_L = 250 \Omega$; $V_{GS} = 4.5 V$	-	15	30	ns
t_r	rise time	$R_{G(ext)} = 6 \Omega$; $T_j = 25^\circ C$	-	11	-	ns
$t_{d(off)}$	turn-off delay time		-	69	138	ns
t_f	fall time		-	19	-	ns
Source-drain diode (per transistor)						
V_{SD}	source-drain voltage	$I_S = 350 mA$; $V_{GS} = 0 V$; $T_j = 25^\circ C$	0.47	0.85	1.2	V

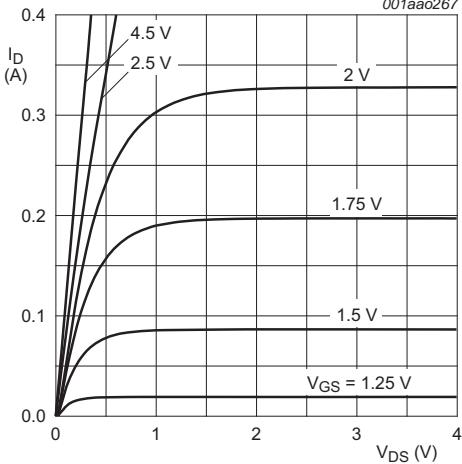


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

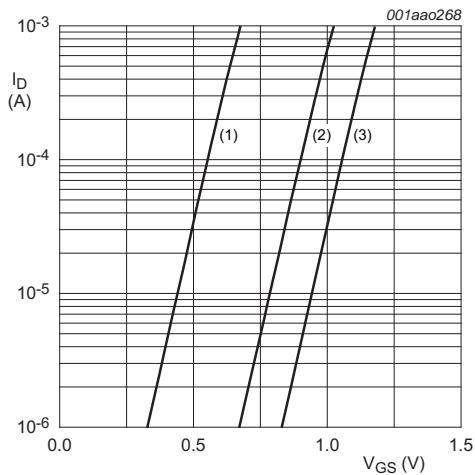


Fig 7. Sub-threshold drain current as a function of gate-source voltage

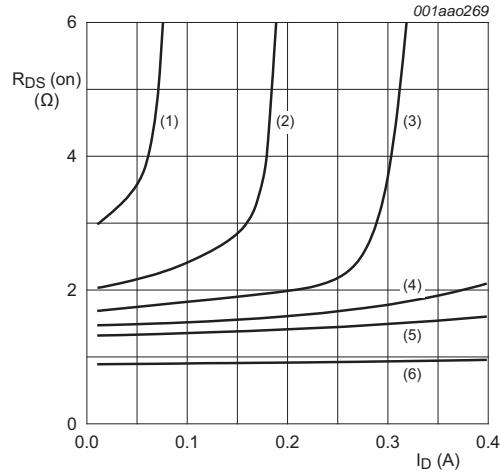


Fig 8. Drain-source on-state resistance as a function of drain current; typical values

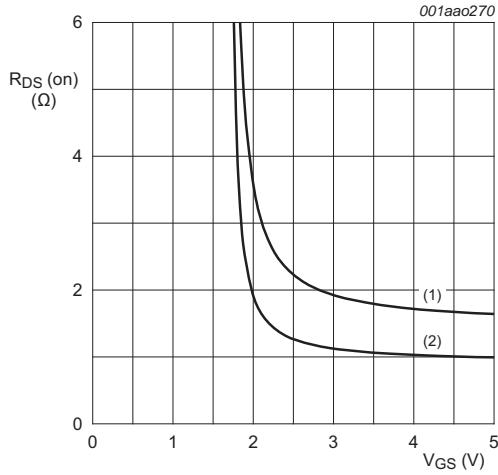
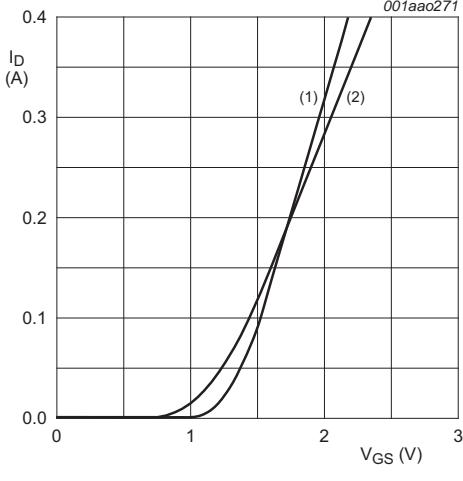


Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

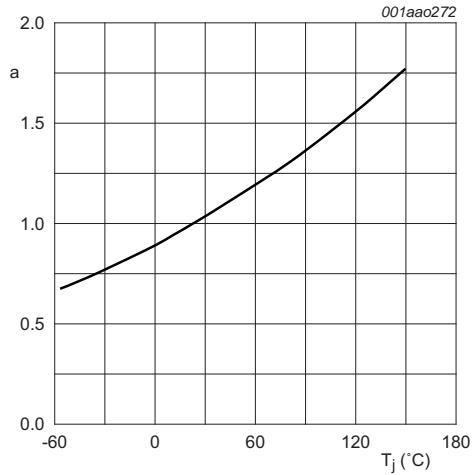


$V_{DS} > I_D \times R_{DSon}$

(1) $T_j = 25 \text{ } ^\circ\text{C}$

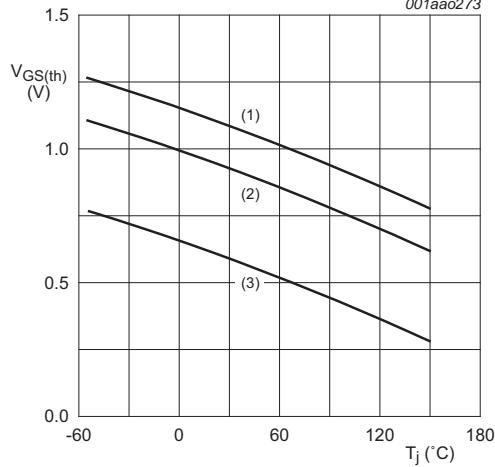
(2) $T_j = 150 \text{ } ^\circ\text{C}$

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



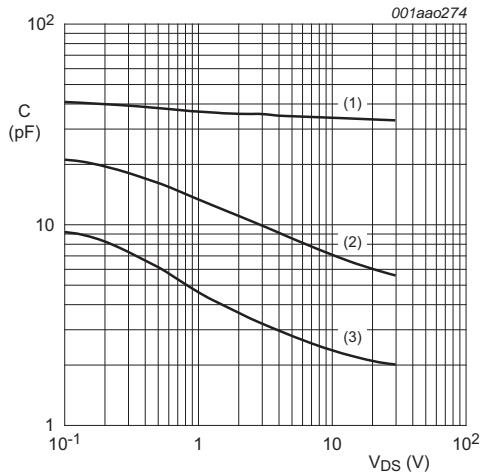
$I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}$

(1) maximum values

(2) typical values

(3) minimum values

Fig 12. Gate-source threshold voltage as a function of junction temperature



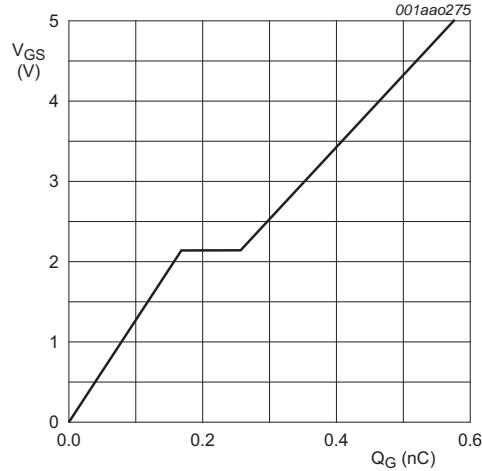
$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$

(1) C_{iss}

(2) C_{oss}

(3) C_{rss}

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 0.4$ A; $V_{DS} = 15$ V; $T_{amb} = 25$ °C

Fig 14. Gate-source voltage as a function of gate charge; typical values

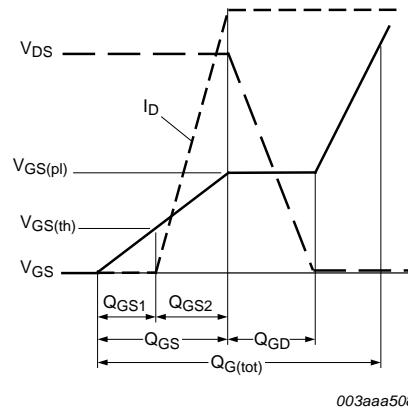
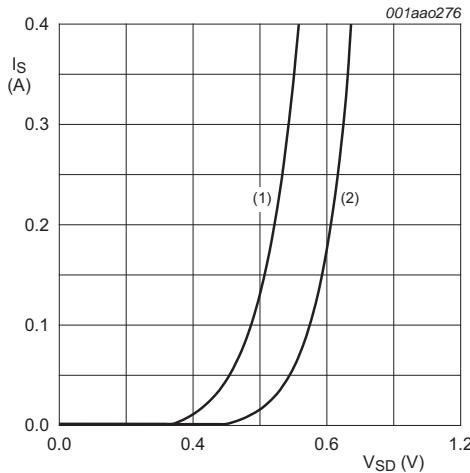


Fig 15. Gate charge waveform definitions



$V_{GS} = 0$ V

(1) $T_j = 150$ °C

(2) $T_j = 25$ °C

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information

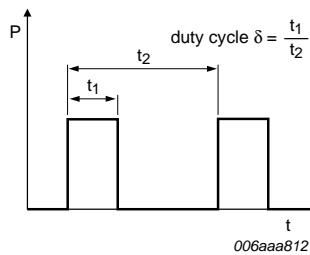


Fig 17. Duty cycle definition

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

Plastic surface-mounted package; 6 leads

SOT666

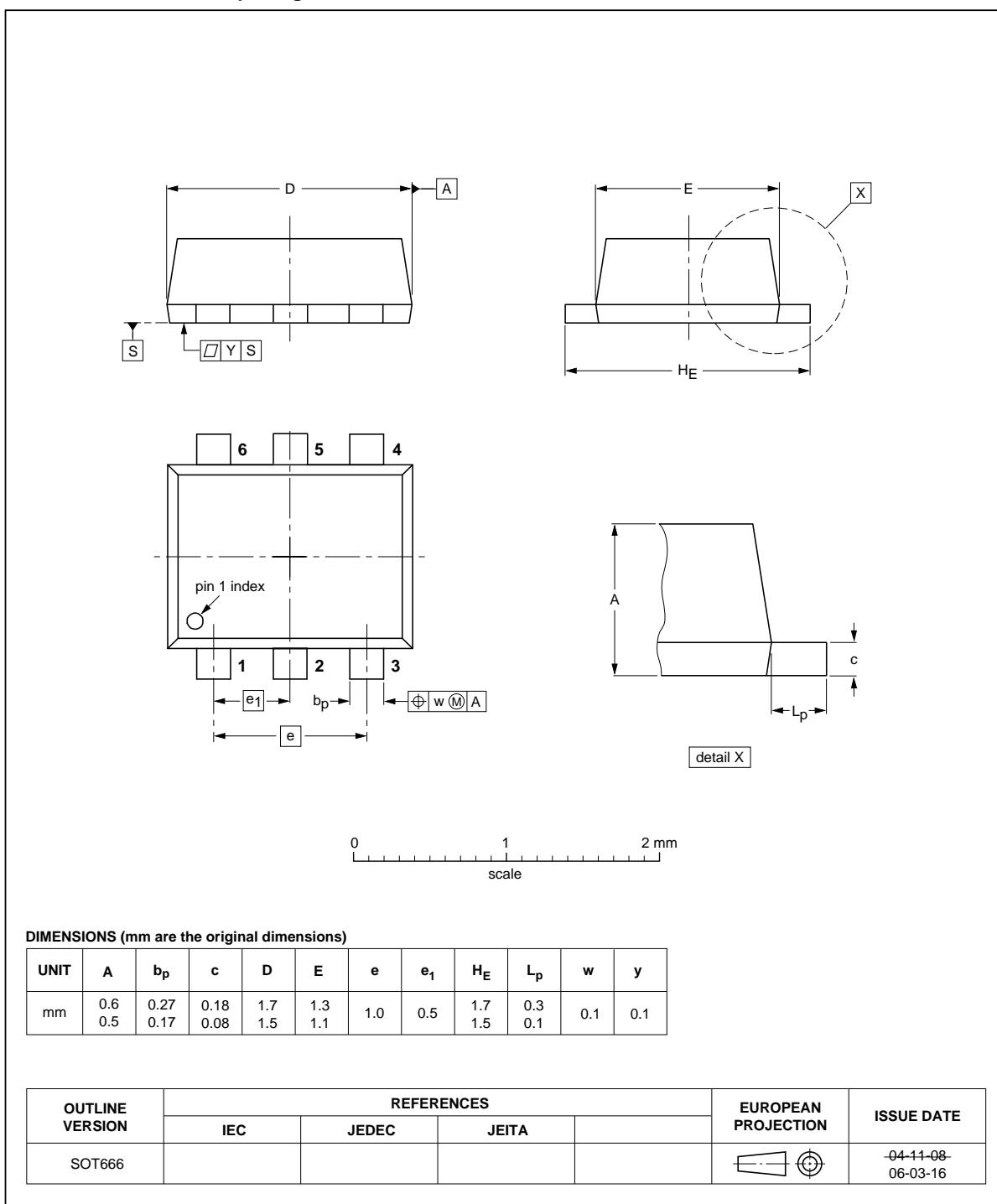


Fig 18. Package outline SOT666 (SOT666)

10. Soldering

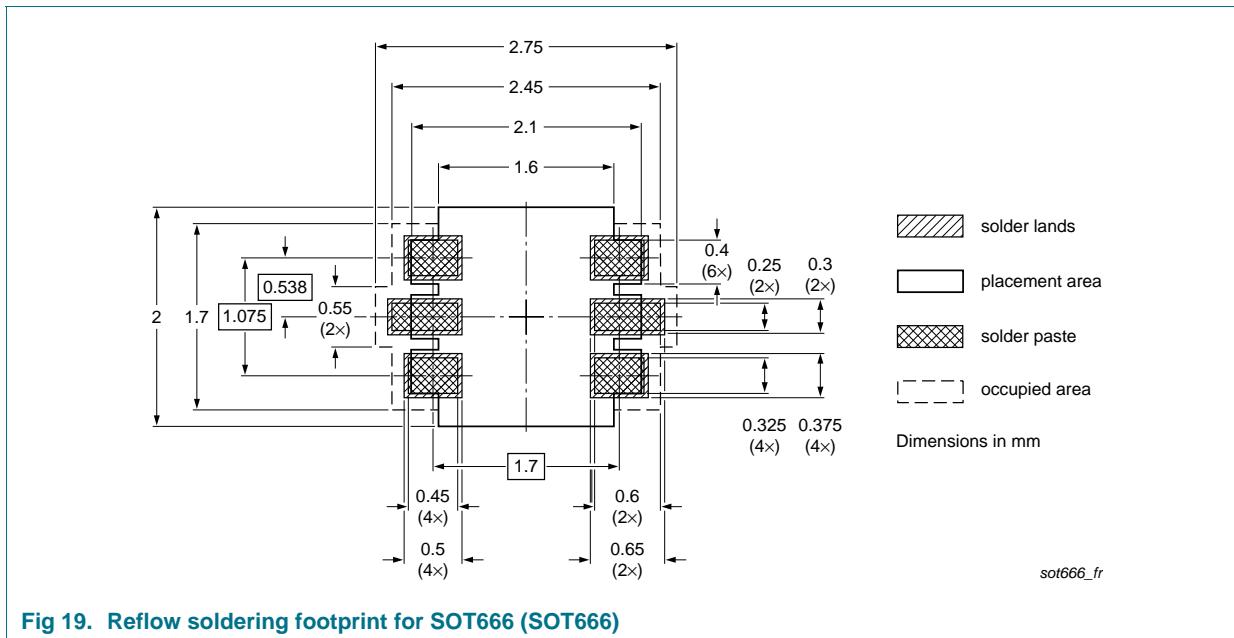


Fig 19. Reflow soldering footprint for SOT666 (SOT666)

11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NX3008NBKV v.1	20110801	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^[1] ^[2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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